

**DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION**  
**(37 C.F.R. §1.63)**

As a below named inventor, I hereby declare:

My residence, mailing address, and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor or an original, first and joint inventor of the subject matter that is claimed and for which a patent is sought on the invention entitled:

**SEMICONDUCTOR COMPONENT WITH INTEGRATED CAPACITANCE STRUCTURE HAVING A PLURALITY OF METALLIZATION PLANES**

the specification of which (check one)

☒ is attached hereto.

☐ was filed on \_\_\_\_\_ as United States Application No. \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge my duty to disclose to the United States Patent and Trademark Office all information that I know to be material to the patentability of this application as defined in 37 C.F.R. §1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim foreign priority benefits under 35 U.S.C. §119(a)-(d) or (f), or §365(b) of any foreign application(s) for patent or inventor's or plant breeder's rights certificate(s), or §365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's or plant breeder's rights certificate(s) or PCT International application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s):			Priority <u>Not Claimed</u>
<u>PCT/DE03/01304</u> (Number)	<u>PCT</u> (Country)	<u>04/17/2003</u> (Filing Date, MM/DD/YYYY)	<input type="checkbox"/>
<u>102 17 566.7</u> (Number)	<u>Germany</u> (Country)	<u>04/19/2002</u> (Filing Date, MM/DD/YYYY)	<input type="checkbox"/>

I hereby claim the benefit under 35 U.S.C. §119(e) of any United States provisional application(s) listed below:

<u>(Application Serial No.)</u>	<u>(Filing Date, MM/DD/YYYY)</u>	<u>(Status: pending, or abandoned)</u>
<u>(Application Serial No.)</u>	<u>(Filing Date, MM/DD/YYYY)</u>	<u>(Status: pending, or abandoned)</u>

I hereby claim the benefit under 35 U.S.C. §120 of any United States applications(s), or §365(c) of any PCT International Application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. §112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. §1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

(Application Serial No.)	(Filing Date, MM/DD/YYYY)	(Status: patented, pending, abandoned)
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. §1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor <b>Hichem ABDALLAH</b>	
Sole or first inventor's signature	Date
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Second inventor's signature	Date
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